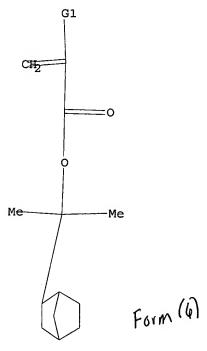
16/648,243: CARIS. File struc. search cl. 1, form 1-3,6, 4/25/06, RPA als W/ Nb-lactore, 4/25/06, RPA

(FILE 'HOME' ENTERED AT 17:47:14 ON 25 JUN 2006)

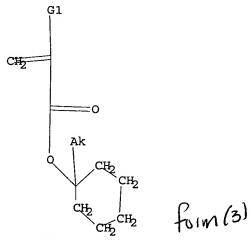
```
FILE 'REGISTRY' ENTERED AT 17:47:38 ON 25 JUN 2006
                SCREEN 963 AND 970 AND 2067
L1
L2
                STRUCTURE UPLOADED
L3
                QUE L2 AND L1
L4
                SCREEN 970 AND 2067
L5
                STRUCTURE UPLOADED
                QUE L5 AND L4
L6
                SCREEN 970 AND 2067
L7
                STRUCTURE UPLOADED
L8
L9
                QUE L8 AND L7
                SCREEN 970 AND 2067
L10
                STRUCTURE UPLOADED
L11
L12
                QUE L11 AND L10
=> d 13
L3 HAS NO ANSWERS
                SCR 963 AND 970 AND 2067
L2
                STR
```



G1 H, Me

Structure attributes must be viewed using STN Express query preparation. L3 $\,$ QUE L2 AND L1 $\,$

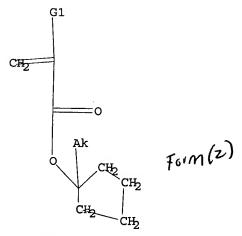
```
=> d 16
L6 HAS NO ANSWERS
L4 SCR 970 AND 2067
L5 STR
```



G1 H, Me

Structure attributes must be viewed using STN Express query preparation. L6 $\,$ QUE $\,$ L5 AND L4 $\,$

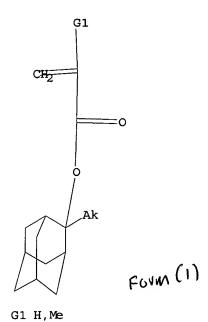
=> d 19 L9 HAS NO ANSWERS L7 SCR 970 AND 2067 L8 STR



G1 H, Me

Structure attributes must be viewed using STN Express query preparation. L9 $$\tt QUE \tt L8 \ AND \ L7$$

=> d 112 L12 HAS NO ANSWERS L10 SCR 970 AND 2067 L11 STR



Structure attributes must be viewed using STN Express query preparation. QUE L11 AND L10 L12

=> d his

(FILE 'HOME' ENTERED AT 17:47:14 ON 25 JUN 2006)

FILE 'REGISTRY' ENTERED AT 17:47:38 ON 25 JUN 2006 L1SCREEN 963 AND 970 AND 2067 L2STRUCTURE UPLOADED L3 QUE L2 AND L1 L4SCREEN 970 AND 2067 L5STRUCTURE UPLOADED L6 QUE L5 AND L4 L7SCREEN 970 AND 2067 rsSTRUCTURE UPLOADED L9 QUE L8 AND L7 L10 SCREEN 970 AND 2067 STRUCTURE UPLOADED L11L12 QUE L11 AND L10

=>

```
FILE 'REGISTRY' ENTERED AT 17:47:38 ON 25 JUN 2006
                SCREEN 963 AND 970 AND 2067
L1
                STRUCTURE UPLOADED
L2
L3
                QUE L2 AND L1
L4
                SCREEN 970 AND 2067
                STRUCTURE UPLOADED
L5
                QUE L5 AND L4
L6
                SCREEN 970 AND 2067
L7
               STRUCTURE UPLOADED
L8
               QUE L8 AND L7
L9
L10
               SCREEN 970 AND 2067
               STRUCTURE UPLOADED
L11
L12
               QUE L11 AND L10
            58 S L3 FULL FORM 6
L13
           165 S L6 FULL Poin 3
L14
           283 S L9 FULL FOWAZ
L15
          1882 S L12 FULL FORM |
L16
L17
             1 S L13 AND (L14 OR 15 OR 16)
```

FILE 'CAPLUS' ENTERED AT 17:54:20 ON 25 JUN 2006 L18 1 S L17

FILE 'REGISTRY' ENTERED AT 17:55:22 ON 25 JUN 2006

=> s l14 and (l15 or l14 or l16) L19 165 L14 AND (L15 OR L14 OR L16)

=> d 1-40 bib hitstr

. . . .

'BIB' IS NOT A VALID FORMAT FOR FILE 'REGISTRY'

'HITSTR' IS NOT A VALID FORMAT FOR FILE 'REGISTRY'

The following are valid formats:

Substanc

3 58 S L3 FULL L14 165 S L6 FULL L15 283 S L9 FULL L16 1882 S L12 FULL L17 1 S L13 AND (L14 OR 15 OR 16) FILE 'CAPLUS' ENTERED AT 17:54:20 ON 25 JUN 2006 => s 117 L18 1 L17 => d bib L18 ANSWER 1 OF 1 CAPLUS COPYRIGHT 2006 ACS on STN AN2003:855512 CAPLUS DN 139:343483 TI Radiation-sensitive resin composition Nishimura, Yukio; Ishii, Hiroyuki; Yamamoto, Masafumi; Nishimura, Isao IN PA U.S. Pat. Appl. Publ., 26 pp. SO CODEN: USXXCO DT Patent LA English FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 2003203309	A1	20031030	US 2003-386707	20030313
	JP 2003337419	A2	20031128	JP 2003-66164	20030312
PRAI	JP 2002-71696	Α	20020315		

```
L20 ANSWER 29 OF 32 CAPLUS COPYRIGHT 2006 ACS on STN
```

AN 2003:855512 CAPLUS

DN 139:343483

TI Radiation-sensitive resin composition

IN Nishimura, Yukio; Ishii, Hiroyuki; Yamamoto, Masafumi; Nishimura, Isao

PA Japar

SO U.S. Pat. Appl. Publ., 26 pp.

CODEN: USXXCO

DT Patent

LA English

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 2003203309	A1	20031030	US 2003-386707	20030313
	JP 2003337419	A2	20031128	JP 2003-66164	20030312
PRAI	JP 2002-71696	A	20020315		

AB A radiation-sensitive resin composition suitable as a chemical amplified resist useful for microfabrication comprises: (A) a resin insol. or scarcely soluble in alkali, but becomes alkali soluble by the action of an acid and (B) a photoacid generator. The resin comprises at least one recurring unit of the following formula I (R1 = H, methyl; A1 = single bond, X1-COO-; X1 = methylene, alkylene with less with 10 carbon atoms; R2 = C1-6 alkyl; n = 0, 1; R3 = H, C1-6 alkyl, oxygen containing group), II (R4 = H, methyl; A2 = single bond, X2-COO-; X2 = methylene, alkylene with less with 10 carbon atoms; R5 = C1-4 alkyl, C4-20 monovalent alicycli hydrocarbon group).

IT 617711-90-7P 617711-95-2P

RL: PRP (Properties); SPN (Synthetic preparation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(radiation-sensitive resin composition for microfabrication containing)

RN 617711-90-7 CAPLUS

CN 2-Propenoic acid, 2-methyl-, 1-ethylcyclopentyl ester, polymer with hexahydro-2-oxo-3,5-methano-2H-cyclopenta[b] furan-6-yl

2-methyl-2-propenoate, 2-methyltricyclo[3.3.1.13,7]dec-2-yl

2-methyl-2-propenoate and (tetrahydro-3,3-dimethyl-5-oxo-2-furanyl)methyl

2-methyl-2-propenoate (9CI) (CA INDEX NAME)

CM 1

CRN 379257-69-9 CMF C11 H16 O4

$$\begin{array}{c|c} \text{O} & \text{CH}_2 \\ \parallel & \parallel \\ \text{Me} \\ \text{Me} \end{array}$$

CM 2

CRN 266308-58-1 CMF C11 H18 O2 May a froit

CM 3

CRN 254900-07-7 CMF C12 H14 O4

CM 4

CRN 177080-67-0 CMF C15 H22 O2

RN 617711-95-2 CAPLUS

2-Propenoic acid, 2-methyl-, hexahydro-2-oxo-3,5-methano-2H-cyclopenta[b] furan-6-yl ester, polymer with 1-methylcyclopentyl 2-methyl-2-propenoate, 2-methyltricyclo[3.3.1.13,7]dec-2-yl 2-methyl-2-propenoate and 5-[3,3,3-trifluoro-2-hydroxy-2-(trifluoromethyl)propyl]bicyclo[2.2.1]hept-2-yl 2-methyl-2-propenoate (9CI) (CA INDEX NAME)

CM 1

CN

CRN 617711-94-1 CMF C15 H18 F6 O3

$$\begin{array}{c} \text{OH} \\ | \\ \text{CH}_2\text{C} \\ | \\ | \\ \text{Me-} \text{C-} \text{C-} \text{O} \end{array}$$

CM 2

CRN 254900-07-7 CMF C12 H14 O4

CM 3

CRN 178889-45-7 CMF C10 H16 O2

CM 4

CRN 177080-67-0 CMF C15 H22 O2

L20 ANSWER 31 OF 32 CAPLUS COPYRIGHT 2006 ACS on STN

AN 2002:84088 CAPLUS

DN 136:119239

TI New copolymers for deep UV workable photoresists with good light transmittance and high sensitivity and resolution and method for forming resist patterns with high aspect ratio using the copolymers

IN Nakamura, Takeshi; Ikegawa, Taeko; Sawano, Atsushi; Doi, Kosuke; Ohara, Hidekatsu

PA Tokyo Ohka Kogyo Co., Ltd., Japan

SO Jpn. Kokai Tokkyo Koho, 14 pp. CODEN: JKXXAF

DT Patent

LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2002030116	A2	20020131	JP 2000-214450	20000714
	TW 556046	В	20031001	TW 2001-90116169	20010702

US	2002031719	A1	20020314	US	2001-901646	20010711
US	6517993	B2	20030211			
DE	10134162	A1	20020425	DE	2001-10134162	20010713
DE	10134162	B4	20051020			
PRAI JP	2000-214450	A	20000714			

AB The copolymers bear units derived from (meth)acrylic acid 1-(C1-4 alkyl)cyclohexyl esters, unsatd. acid anhydrides, and optionally allyltrimethylsilane or/and 2-(C1-4 alkyl)-2-adamantyl (meth)acrylate, and are used in a photoresist composition containing photochem. acid formers and organic

solvents. Thus, mixing 1-ethyl-1-cyclohexyl methacrylate 7.4 with 2-methyl-2-adamantyl methacrylate 5.3, maleic anhydride 0.9, allyltrimethylsilane 7.3 and AIBN 0.6 in EtOAc 69.4 parts at room temperature for 60 min, heating at 70° for 22 h and working up gave a copolymer with Mw 18,400 and polydispersity 1.54, which was dissolved in propylene glycol monomethyl ether acetate to 7% concentration, mixed at 30 g with 4-(MeO)C6H4(Ph)2S+C4F9SO3- 0.258 g, and filtered to give a photoresist with photo-sensitivity 60 J/cm2, resolution 0.17 μm and focusing deep width 0.5 μm .

IT 391208-99-4P, Allyltrimethylsilane;1-ethyl-1-cyclohexyl
methacrylate;maleic anhydride;2-methyl-2-adamantyl methacrylate copolymer
RL: IMF (Industrial manufacture); PRP (Properties); TEM (Technical or
engineered material use); PREP (Preparation); USES (Uses)

(new copolymers for deep UV workable photoresists with good light transmittance and high sensitivity and resolution and method for forming resist patterns with high aspect ratio using copolymers)

RN 391208-99-4 CAPLUS

CN 2-Propenoic acid, 2-methyl-, 2-methyltricyclo[3.3.1.13,7]dec-2-yl ester, polymer with 1-ethylcyclohexyl 2-methyl-2-propenoate, 2,5-furandione and trimethyl-2-propenylsilane (9CI) (CA INDEX NAME)

CM 1

CRN 274248-09-8 CMF C12 H20 O2

CM 2

CRN 177080-67-0 CMF C15 H22 O2

CRN 762-72-1 CMF C6 H14 Si

 $Me_3Si-CH_2-CH \longrightarrow CH_2$

CM 4

CRN 108-31-6 CMF C4 H2 O3

L20 ANSWER 32 OF 32 CAPLUS COPYRIGHT 2006 ACS on STN

AN 2000:624801 CAPLUS

DN 133:215460

TI Positive-working far UV-sensitive resist composition

IN Kodama, Kunihiko; Sato, Kenichiro; Aogo, Toshiaki

PA Fuji Photo Film Co., Ltd., Japan

SO Jpn. Kokai Tokkyo Koho, 36 pp.

CODEN: JKXXAF

DT Patent

LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
ΡI	JP 2000241977	A2	20000908	JP 1999-44978	19990223
PRAI	JP 1999-44978		19990223		

The pos.-working far UV-sensitive resist composition has a photoacid generator and a resin, which has -O-C(R')(R'')(X-COR) (R', R'' = alkyl, cyclic hydrocarbon; X = single bond, divalent connecting group; R = alkoxy, amide, amino, etc.) group in the side chain, increasing the solubility towards an alkali developer upon reacting with an acid. The composition having the resin is suitable for exposure with ≤ 250 nm far UV light.

IT 290304-61-9P

RL: PNU (Preparation, unclassified); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(resin in pos.-working far UV sensitive resist composition)

RN 290304-61-9 CAPLUS

CN Cyclohexaneacetic acid, 1-[(2-methyl-1-oxo-2-propenyl)oxy]-, polymer with 2-methyltricyclo[3.3.1.13,7]dec-2-yl 2-methyl-2-propenoate (9CI) (CA INDEX NAME)

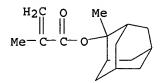
CM 1

CRN 290304-60-8 CMF C12 H18 O4

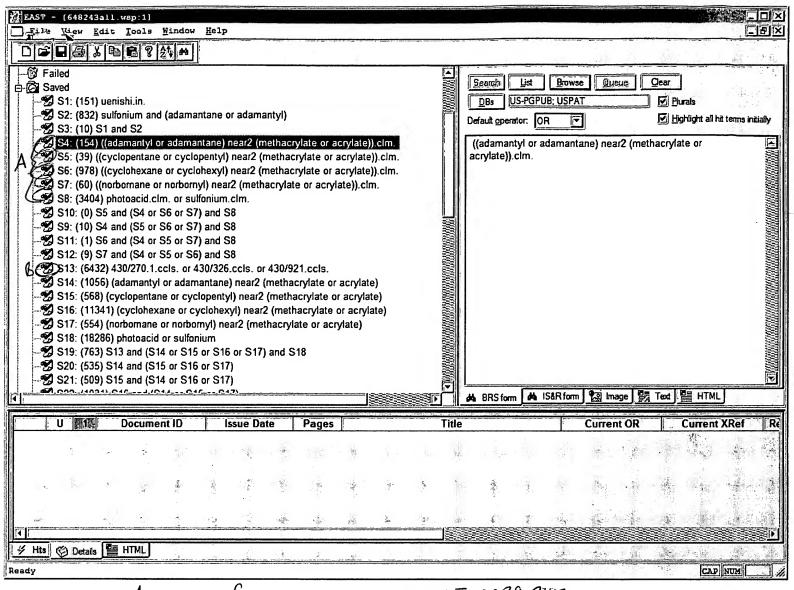
CM 2

~ · · · ·

CRN 177080-67-0 CMF C15 H22 O2



=>



A= interference search, USPAT, USPAPUR

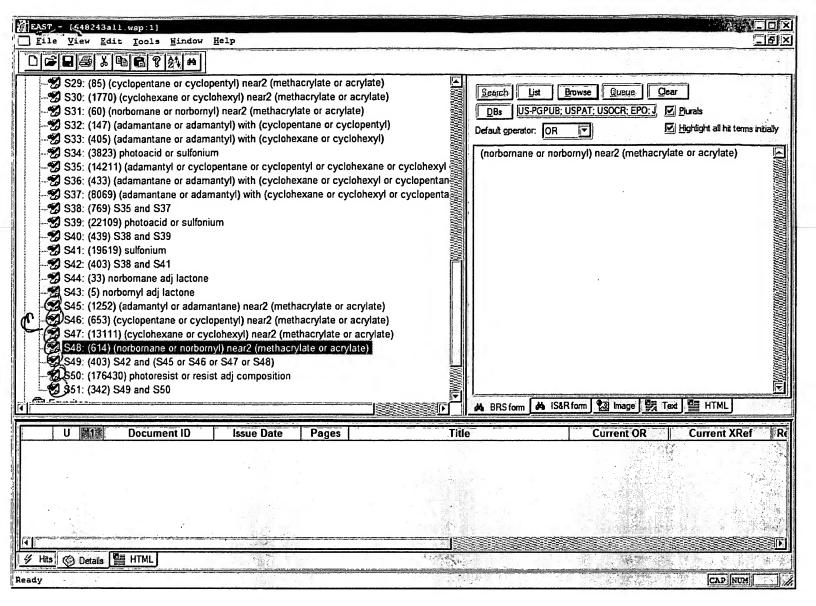
B= e/255 search

c= Text search (on next page)

10/648,243,

searches A-C (above)

4/25/06/78+



C=Textsearch, uspet, uspapuls, epo, spo, perwent, IBM-40
6/25/07, RAM